

客户图

NOTES:

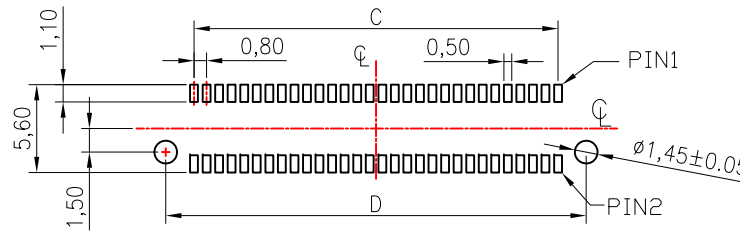
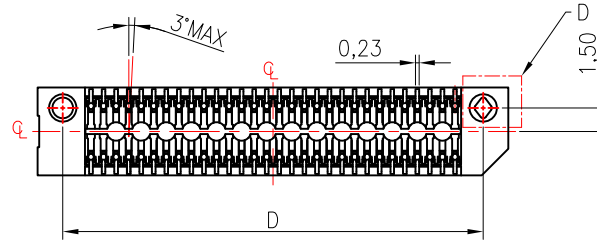
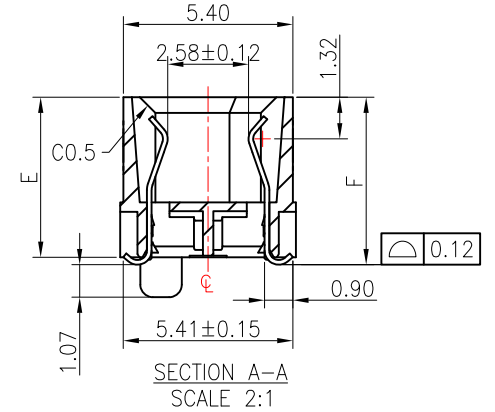
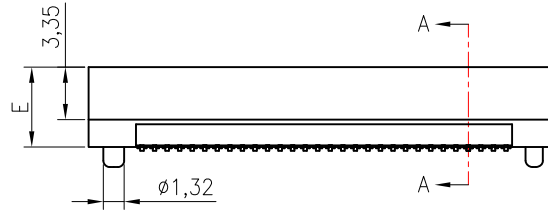
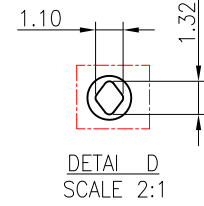
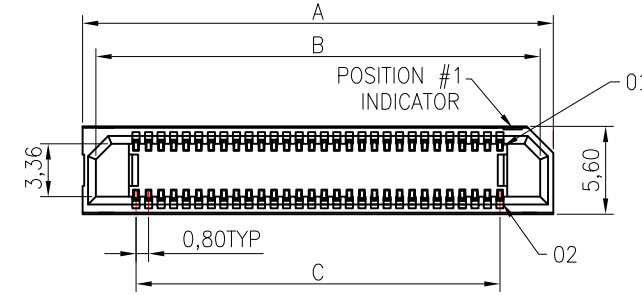
1. FINISH:
 - 1.1 HOUSING: LCP BLACK,UL94V-0.
 - 1.2 CONTACT: BeCu,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA,50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 2 A PER PIN(2 PINS POWERED).
 - 2.2 VOLTAGE RATING: 225V AC/318V DC.
 - 2.3 OPERATION TEMPERATURE:-55°C TO +125°C.
- 3.BURR ALLOWANCE: 0.038 Max.
- 4.MINIMUM PUSHOUT FORCE: 2.22N.
- 5.-TR PACKAGING NOT AVAILABLE ON THE 100POSITION.
-TY PACKAGING ONLY AVAILABLE ON-100 POSITION.
- 6.ORDER INFORMATION:

66C4-F XXX XX XXX R 01

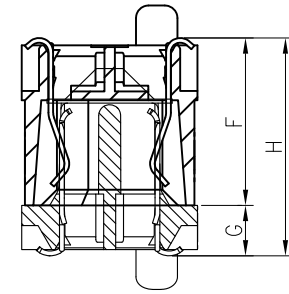
Pin 数码	端子电镀:	塑胶高度:	包装方式:
010=2*5PIN	G0=Gold Flash(全金)	050=5.00mm	R=载带包装
.....	G1=1u" Gold	070=7.00mm	
	G2=3u" Gold		
	G3=5u" Gold		
	G4=10u" Gold		
	G6=30u" Gold		

POSITION	A	B	C	D
010=2*05PIN	10.00	8.32	3.20	6.80
020=2*10PIN	14.00	12.32	7.20	10.80
030=2*15PIN	18.00	16.32	11.20	14.80
040=2*20PIN	22.00	20.32	15.20	18.80
060=2*30PIN	30.00	28.32	23.20	26.80
080=2*40PIN	38.00	36.32	31.20	34.80
100=2*50PIN	46.00	44.32	39.20	42.80
120=2*60PIN	54.00	52.32	47.20	50.80
150=2*75PIN	66.00	64.32	59.20	62.80

STACK HEIGHT	E	F
5.0mm	5.10	5.435
7.0mm	7.00	7.235
9.0mm	9.00	9.235



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



MATING HEIGHT
SCALE 2:1

F	G	H
5.435	1.605	7.00
	4.605	10.00
	8.605	14.00
7.235	1.605	9.00
	8.605	16.00
9.235	1.605	11.00
	4.605	14.00
	8.605	18.00

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW		WLY		SOLEPIN 东莞市硕品电子有限公司			
					DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	SIZE	A4	PART NO.
AO		NEW			X.X	±0.40	DESIGN	Jensen	2017.03.20	Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.XX	±0.25	CHECK	Jack	2017.03.20	SHEET	1/1	TITLE:	BTB 0.8mm CONNECTOR/F	
					X.XXX	±0.15	APPROVE	Andy	2017.03.20	PROJ.	☞	DRAW NO.	SP-526	
					Angle	±3°								

客户图

NOTES:

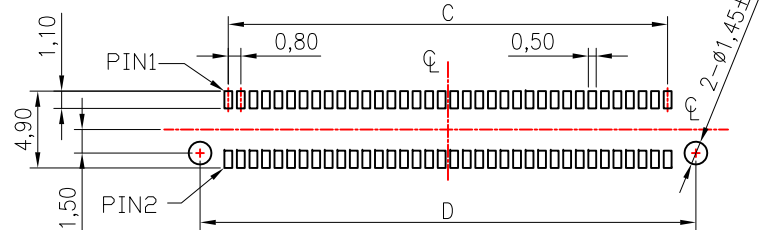
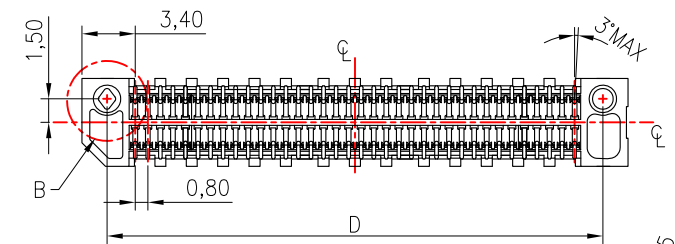
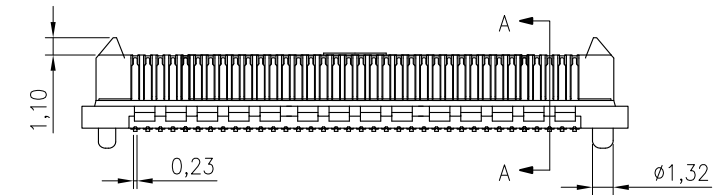
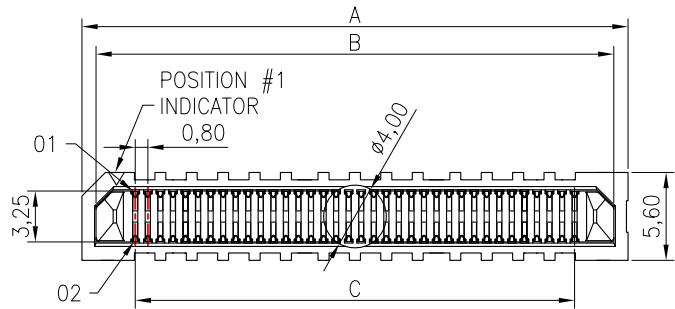
1. FINISH:
 - 1.1 HOUSING: LCP BLACK,UL94V-0.
 - 1.2 CONTACT: BeCu,GOLD (SEE P/N) PLATED
IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN
SOLDER AREA,50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 2 A PER PIN(2 PINS POWERED).
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- 3.BURR ALLOWANCE: 0.038 Max.
- 4.MINIMUM PUSHOUT FORCE: 2.22N.
- 5.-TR PACKAGING NOT AVAILABLE ON THE 100POSITION.
-TY PACKAGING ONLY AVAILABLE ON-100 POSITION.
- 6.ORDER INFORMATION:

66C4-M XXX XX XXX R 01

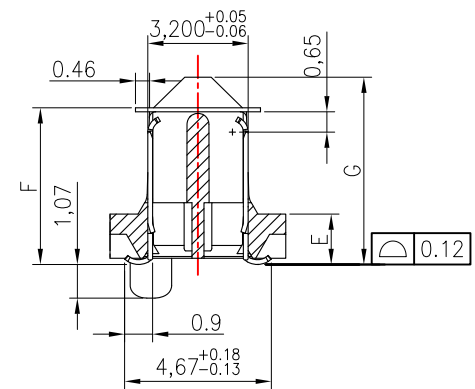
Pin数码	端子电镀:	塑胶高度:	包装方式:
040=2*20PIN	G0=Gold Flash(全金)	020=2.00mm	R=载带包装
.....	G1=1u" Gold	050=5.00mm	
	G2=3u" Gold	090=9.00mm	
	G3=5u" Gold		
	G4=10u" Gold		
	G6=30u" Gold		

POSITION	A	B	C	D
010=2*05PIN	10.00	8.20	3.20	6.80
020=2*10PIN	14.00	12.20	7.20	10.80
024=2*12PIN	15.60	13.80	8.80	12.40
030=2*15PIN	18.00	16.20	11.20	14.80
040=2*20PIN	22.00	20.20	15.20	18.80
060=2*30PIN	30.00	28.20	23.20	26.80
080=2*40PIN	38.00	36.20	31.20	34.80
100=2*50PIN	46.00	44.20	39.20	42.80
120=2*60PIN	54.00	52.20	47.20	50.80
150=2*75PIN	66.00	64.20	59.20	62.80

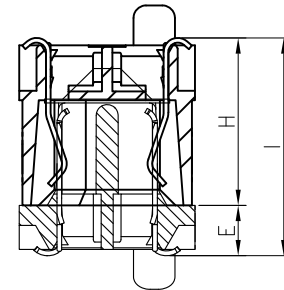
STACK HEIGHT	E	F	G
2.00	1.605	5.04	5.97
5.00	4.605	8.04	8.97
9.00	8.605	12.04	12.97
15.00	14.605	18.04	18.97



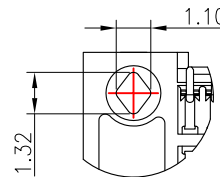
RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



SECTION A-A
SCALE 2:1



MATING HEIGHT
SCALE 2:1



DETAIL 'B'
SCALE 2:1

E	H	I
1.605	5.435	7.00
	7.235	9.00
	9.235	11.00
4.605	5.435	10.00
	7.235	12.00
	9.235	14.00
7.605	5.435	13.00
	7.235	15.00
	9.235	17.00
8.605	5.435	14.00
	7.235	16.00
	9.235	18.00
14.605	5.435	20.00
	7.235	22.00
	9.235	24.00

OPERATION

DRAW WLY 2017.03.20

X.X ±0.40 DESIGN Jensen 2017.03.20

X.XX ±0.25 CHECK Jack 2017.03.20

X.XXX ±0.15 APPROVE Andy 2017.03.20

Angle ±3°

DIM. TOL UNIT mm SCALE 1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 66C4-MXXXXXXXXR01

SHEET 1/1 TITLE: BTB 0.8mm CONNECTOR/M

PROJ. DRAW NO. SP-364

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
AO		NEW		